



BSI Standards Publication

Semiconductor devices – Mechanical and climatic test methods

Part 13: Salt atmosphere

National foreword

This British Standard is the UK implementation of EN IEC 60749-13:2018. It is identical to IEC 60749-13:2018. It supersedes BS EN 60749-13:2002, which is withdrawn.

The UK participation in its preparation was entrusted to Technical Committee EPL/47, Semiconductors.

A list of organizations represented on this committee can be obtained on request to its secretary.

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English Version

**Semiconductor devices - Mechanical and climatic test methods -
Part 13: Salt atmosphere
(IEC 60749-13:2018)**

Dispositifs à semiconducteurs - Méthodes d'essais
mécaniques et climatiques - Partie 13: Atmosphère saline
(IEC 60749-13:2018)

Halbleiterbauelemente - Mechanische und klimatische
Prüfverfahren - Teil 13: Salzatmosphäre
(IEC 60749-13:2018)

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European Committee for Electrotechnical Standardization
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European foreword

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This document supersedes EN 60749-13:2002.

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Endorsement notice

The text of the International Standard IEC 60749-13:2018 was approved by CENELEC as a European Standard without any modification.

Annex ZA (normative)

Normative references to international publications with their corresponding European publications

The following documents are referred to in the text in such a way that some or all of their content constitutes requirements of this document. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.

NOTE 1 Where an International Publication has been modified by common modifications, indicated by (mod), the relevant EN/HD applies.

NOTE 2 Up-to-date information on the latest versions of the European Standards listed in this annex is available here: www.cenelec.eu.

<u>Publication</u>	<u>Year</u>	<u>Title</u>	<u>EN/HD</u>	<u>Year</u>
IEC 60749-14	-	Semiconductor devices - Mechanical and climatic test methods -- Part 14: Robustness of terminations (lead integrity)	EN 60749-14	-

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